



US 20240237209A9

(19) **United States**
(12) **Patent Application Publication**
Lin et al.

(10) **Pub. No.: US 2024/0237209 A9**
(48) **Pub. Date: Jul. 11, 2024**
CORRECTED PUBLICATION

(54) **CIRCUIT BOARD STRUCTURE AND
MANUFACTURING METHOD THEREOF**

Publication Classification

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(21) Appl. No.: **17/986,899**

(22) Filed: **Nov. 15, 2022**

Prior Publication Data

(15) Correction of US 2024/0138063 A1 Apr. 25, 2024
See (30) Foreign Application Data.

(65) US 2024/0138063 A1 Apr. 25, 2024

(30) **Foreign Application Priority Data**

Oct. 21, 2022 (TW) 111139982

(51) **Int. Cl.**

H05K 1/11 (2006.01)
H05K 1/02 (2006.01)
H05K 3/34 (2006.01)
H05K 3/40 (2006.01)

(52) **U.S. Cl.**

CPC **H05K 1/114** (2013.01); **H05K 1/024**
(2013.01); **H05K 3/3442** (2013.01); **H05K**
3/4007 (2013.01); **H05K 2201/0195** (2013.01);
H05K 2203/041 (2013.01)

(57)

ABSTRACT

A circuit board structure includes a carrier, a thin film redistribution layer disposed on the carrier, solder balls electrically connected to the thin film redistribution layer and the carrier, and a surface treatment layer. The thin film redistribution layer includes a plurality of pads, a first dielectric layer, a first metal layer, a second dielectric layer, a second metal layer, and a third dielectric layer. A plurality of first openings of the first dielectric layer expose part of the pads, and a first surface of the first dielectric layer is higher upper surfaces of the pads. The solder balls are disposed in a plurality of third openings of the third dielectric layer and are electrically connected to the second metal layer and the carrier. The surface treatment layer is disposed on the upper surfaces, and a top surface of the surface treatment layer is higher than the first surface.

